

LID AND METHOD OF EMPLOYING
A LID ON AN INTEGRATED CIRCUIT

ABSTRACT

A lid having a plurality of recesses at the edges of the lid to provide an improved adhesive bond between the lid and a substrate of an integrated circuit is disclosed. The plurality of recesses may be a castellation comprising a collection of semi-circular cuts into the originally straight edges of the lid. The castellation can be formed by stamping, etching, molding design, or milling/drilling, all of which are well-known methods in the art of forming lids for integrated circuits. The castellation can be vertically straight or it can be slightly tapered, to provide a better locking of the lid on to the package. Epoxy in the recesses can provide an epoxy post for locking the lid. Method of forming a lid having a plurality of recesses and employing a lid on an integrated circuit are also disclosed.